

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Chenglin Liu	09/27/2011
Shiann-Ming Liou	09/27/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Marvell Semiconductor, Inc.
<b>Street Address:</b>	5488 Marvell Lane
<b>City:</b>	Santa Clara
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95054
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13247857
<b>CORRESPONDENCE DATA</b>	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Correspondent Name:</b>	Horace Ng
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<b>ATTORNEY DOCKET NUMBER:</b>	MP3838
<b>NAME OF SUBMITTER:</b>	Horace Ng
<b>Total Attachments: 2</b> source=MP3838_EXECUTED ASSIGNMENT INV TO MSI#page1.tif source=MP3838_EXECUTED ASSIGNMENT INV TO MSI#page2.tif	

OP \$40.00 13247857

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned,

**Chenglin Liu and Shiann-Ming Liou**

who have created a certain invention for which an application for United States Letters Patent was executed by me concurrently herewith and entitled:

**PLACING HEAT SINK INTO PACKAGING BY STRIP FORMATION ASSEMBLY**

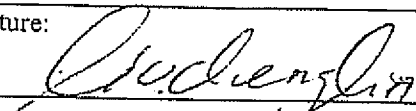
Do hereby sell, assign and transfer to Marvell Semiconductor, Inc., a corporation of California, having a place of business at 5488 Marvell Lane, Santa Clara, CA 95054, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefore in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

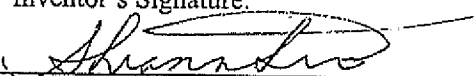
Do hereby further sell, assign and transfer to Marvell Semiconductor, Inc., its successors, assigns, and legal representatives, the full and exclusive right to United States Provisional Patent Applications(s) No(s). 61/389,409, filed October 4, 2010 entitled "PUTTING HEAT SINK INTO PKG BY STRIP FORMATION ASSEMBLY", and 61/392,816, filed October 13, 2010 entitled "HEAT SPREADER EMBEDDED PACKAGE USING FILM-ASSISTED MOLDING SYSTEM" and to any and all inventions described in said provisional patent application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be entitled to the benefit thereof in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that Marvell Semiconductor, Inc., hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below.

Full Name of Inventor:	
Chenglin Liu	
Inventor's Signature:	Date: Month/Day/Year
	9/27/2011

Full Name of Inventor: Shiann-Ming Liou	
Inventor's Signature: 	Date: Month/Day/Year 9/27/2011